

ABSTRACT OF THE DISCLOSURE

The present invention is directed to a laminate having a layer construction of metal-insulating layer-metal or a layer construction of metal-insulating layer, which laminate meets conditions for developing large adhesive strength between the insulating layer and the metal, as well as to an insulating film and an electronic circuit using the laminate. The laminate has a layer construction of first metal layer/insulating layer/second metal layer or a layer construction of metal layer/insulating layer. The insulating layer 1 has a multilayer structure of two or more layers. The layers on the side of the adhesive interface with each metal layer (a copper foil 3 and an SUS foil 4), out of the layers constituting the insulating layer 1, each are a thermoplastic resin layer 2. The minimum value of the storage modulus at a temperature at or above  $T_g$  of the thermoplastic resin layer 2 is not more than  $10^6$  Pa.

106080 "08052360